



Material Content Data Sheet



Sales Product Name	SAK-XC2288I-136F128L AA			Issued		29. August 2013		
MA#	MA001046276							
Package	PG-LQFP-144-16			Weight*		1463.27 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	56.102	3.83	3.83	38340	38340
leadframe	inorganic material	phosphorus	7723-14-0	0.122	0.01		84	
	non noble metal	zinc	7440-66-6	0.489	0.03		334	
	non noble metal	iron	7439-89-6	9.785	0.67		6687	
	non noble metal	copper	7440-50-8	397.309	27.15	27.86	271522	278627
wire	noble metal	gold	7440-57-5	4.458	0.30	0.30	3047	3047
encapsulation	organic material	carbon black	1333-86-4	4.851	0.33		3315	
	plastics	epoxy resin	-	130.985	8.95		89515	
	inorganic material	silicondioxide	60676-86-0	834.420	57.05	66.33	570245	663075
leadfinish	non noble metal	tin	7440-31-5	9.120	0.62	0.62	6233	6233
plating	noble metal	silver	7440-22-4	3.110	0.21	0.21	2126	2126
glue	plastics	epoxy resin	-	3.128	0.21		2138	
	noble metal	silver	7440-22-4	9.385	0.64	0.85	6414	8552
*deviation	< 10%	Sum in total:			100,00			1000000

Important Remarks:

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